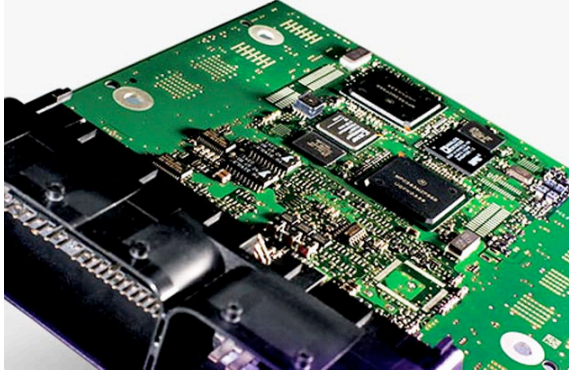


TG-NSP35

ultra conformable silicone-free putty type gap filler





Description

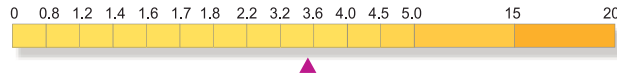
TG-NSP35 is an ultra conformable silicone-free putty type gap filler. It is designed for when heat transfer is needed between delicate components where the pressure must be minimised and silicone contamination cannot be tolerated. TG-NSP35 is designed to fill gaps from 0.25 – 8mm with little or no stress generated. The non-silicone formulation will adhere to all surfaces, such as metal housings, ceramic and plastic IC packages and FR4 boards to give a low thermal resistance path for heat transfer.

TG-NSP35 is available in 30cc syringes, 6 and 12oz cartridges and 5 gallon pails.

Properties

-  REACH Compliant
-  RoHS Compliant

Thermal Conductivity: 3.5 W/mK
(W/mK - Z Axis)



| Property | TG-NSP35 | Unit | Test Method |
|----------------------|-----------------------|--------|-------------|
| Colour | Grey | - | Visual |
| Thermal Conductivity | 3.5 | W/mK | ASTM D5470 |
| Weight Loss | <0.5 | % | ASTM E595 |
| Working Temperature | -40 to 200 | °C | - |
| Volume Resistivity | 2.15×10^{15} | Ohm-cm | ASTM D-257 |
| D4-10 | 0 | PPM | GC / MS |